

## LISTING OF CLAIMS

1-60 (canceled)

61. (previously presented) A contact for making an electrical connection with a component contact on a semiconductor component comprising:

a substrate;

a plurality of spring segment leads having a height on the substrate;

a support member attached to the leads, suspended on the substrate with the height and configured to support the component contact; and

a projection on the support member configured to penetrate the component contact.

62. (previously presented) The contact of claim 61 wherein the leads are configured to twist the projection.

63. (previously presented) The contact of claim 61 wherein the leads have an extensible configuration.

64. (previously presented) The contact of claim 61 wherein the plurality of spring segment leads have a spiral configuration.

65. (previously presented) The contact of claim 61 wherein the support member comprises a plate.

66. (previously presented) The contact of claim 61 wherein the projection comprises a blade.

67. (previously presented) The contact of claim 61 wherein the component contact comprises a bumped contact.

68. (previously presented) The contact of claim 61 further comprising a polymer material between the support member and the substrate.

69. (previously presented) A contact for making an electrical connection with a component contact on a semiconductor component comprising:

- a substrate;

- a plurality of spring segment leads having a height on the substrate;

- a support member attached to the leads, suspended on the substrate with the height and configured to support the component contact and to travel by a distance equal to the height;

- a plurality of conductive vias in the substrate, each spring segment lead in electrical communication with a conductive via; and

- a projection on the support member configured to penetrate the component contact.

70. (previously presented) The contact of claim 69 wherein the support member comprises a plate.

71. (previously presented) The contact of claim 69 further comprising a terminal contact on the substrate in electrical communication with the conductive vias.

72. (previously presented) The contact of claim 69 wherein the spring segment leads are configured to exert a torque on the support member.

73. (previously presented) The contact of claim 69 further comprising a polymer bump between the support member and the substrate.

74. (previously presented) The contact of claim 69 wherein the height is from about 10-25 mils.

75. (previously presented) The contact of claim 69 wherein the component contact comprises a bumped contact.

76. (previously presented) The contact of claim 69 wherein the substrate comprises a semiconductor material.

77. (previously presented) A contact for making an electrical connection with a component contact on a semiconductor component comprising:

- a substrate having a recess;

- a plurality of cantilevered leads on the recess;

- a support member attached to the leads for movement into the recess, the support member configured to support and electrically engage the component contact during the movement into the recess; and

- a projection on the support member.

78. (previously presented) The contact of claim 77 wherein the recess has a depth and the movement into the recess is by an amount approximately equal to the depth.

79. (previously presented) The contact of claim 77 wherein the leads are configured to exert a torque on the support member.

80. (previously presented) The contact of claim 77 wherein the projection comprises a blade configured to penetrate the component contact.

81. (previously presented) The contact of claim 77 wherein the component contact comprises a bumped contact.

82. (previously presented) The contact of claim 77 further comprising a plurality of conductive vias in the substrate in electrical communication with the cantilevered leads.

83. (previously presented) The contact of claim 77 wherein the leads have an extensible configuration.

84. (previously presented) The contact of claim 77 wherein the substrate comprises a semiconductor material.

85. (previously presented) The contact of claim 77 wherein the support member comprises a plate.